

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT4927348

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHOJI HOTTA	03/28/2018
HIROKI KAWADA	03/27/2018
OSAMU INOUE	04/19/2018
RECEIVING PARTY DATA	
Name:	HITACHI HIGH-TECHNOLOGIES CORPORATION
Street Address:	24-14, NISHI-SHIMBASHI 1-CHOME, MINATO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	105-8717
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15305740
CORRESPONDENCE DATA	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Email:	escotti@mmiplaw.com
Correspondent Name:	MATTINGLY & MALUR, PC
Address Line 1:	1800 DIAGONAL ROAD
Address Line 2:	SUITE 210
Address Line 4:	ALEXANDRIA, VIRGINIA 22314
ATTORNEY DOCKET NUMBER:	POL-10650
NAME OF SUBMITTER:	JOHN R. MATTINGLY
SIGNATURE:	/John R. Mattingly/
DATE SIGNED:	04/23/2018
Total Attachments: 3	
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source=10650-Assignment#page2.tif	
source=10650-Assignment#page3.tif	

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by Hitachi High-Technologies Corporation a corporation organized under the laws of Japan, located at 24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo 105-8717, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi High-Technologies Corporation its successor and assigns, all my right, title and interest, in and for the United States of America, in and to

MEASUREMENT SYSTEM AND MEASUREMENT METHOD

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi High-Technologies Corporation its successor, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

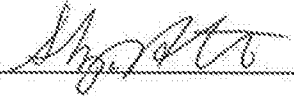
And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi High-Technologies Corporation

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1)		Shoji HOTTA	<u>March 28, 2018</u>
2)		Hiroki KAWADA	
3)		Osamu INOUE	
4)			
5)			
6)			
7)			
8)			
9)			
10)			

PATENT

REEL: 045609 FRAME: 0213

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INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) _____	Shoji HOTTA	_____
2) <u>Hiroki Kawada</u>	Hiroki KAWADA	<u>March 27, 2018</u>
3) _____	Osamu INOUE	_____
4) _____		_____
5) _____		_____
6) _____		_____
7) _____		_____
8) _____		_____
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10) _____		_____

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INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) _____	Shoji HOTTA	_____
2) _____	Hiroki KAWADA	_____
3) <u>Osamu Inoue</u>	Osamu INOUE	<u>April 19, 2018</u>
4) _____		_____
5) _____		_____
6) _____		_____
7) _____		_____
8) _____		_____
9) _____		_____
10) _____		_____